

MURD340T4G, NRVUD340T4G

Switch-mode Power Rectifier

DPAK Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Low Forward Voltage Drop
- Low Leakage
- Ultra-Fast Recovery Time
- NRVUD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 gram (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Reverse Voltage	V_R	400	V
Average Rectified Forward Current	$I_{F(AV)}$	3	A
Nonrepetitive Peak Surge Current	I_{FSM}	75	A
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

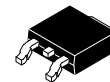
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



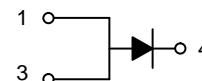
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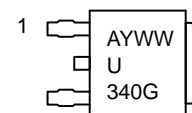
ULTRAFAST RECTIFIER 3 A, 400 V



DPAK
CASE 369C



MARKING DIAGRAM



U340 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping†
MURD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NRVUD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{\theta JC}$	2	$^{\circ}\text{C}/\text{W}$
Thermal Resistance – Junction-to-Ambient (Note 1)	$R_{\theta JA}$	49	$^{\circ}\text{C}/\text{W}$

1. Rating applies when surface mounted on a 700 mm², 1 oz Cu heat spreader.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage ($I_F = 3.0\text{ A}$, $T_J = 25^{\circ}\text{C}$) ($I_F = 3.0\text{ A}$, $T_J = 150^{\circ}\text{C}$)	V_F	1.15 0.92	V
Maximum Instantaneous Reverse Current (Rated V_R) ($T_J = 25^{\circ}\text{C}$, 400 V) ($T_J = 150^{\circ}\text{C}$, 400 V)	I_R	5 500	μA
Maximum Reverse Recovery Time ($I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_J = 25^{\circ}\text{C}$)	t_{rr}	50	ns
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

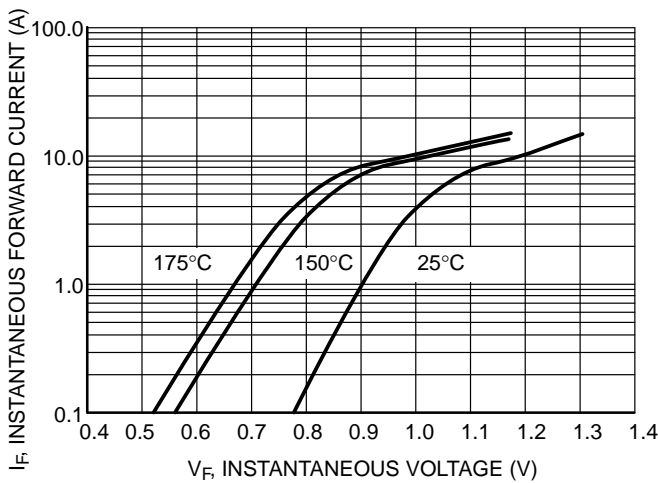


Figure 1. Typical Forward Voltage

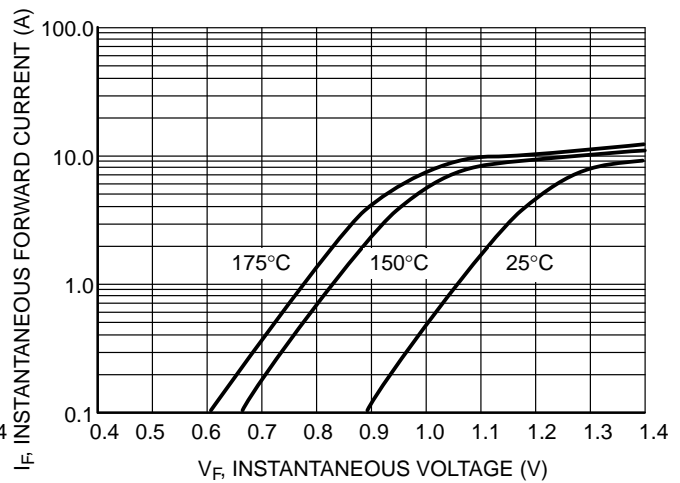


Figure 2. Maximum Forward Voltage

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TYPICAL CHARACTERISTICS

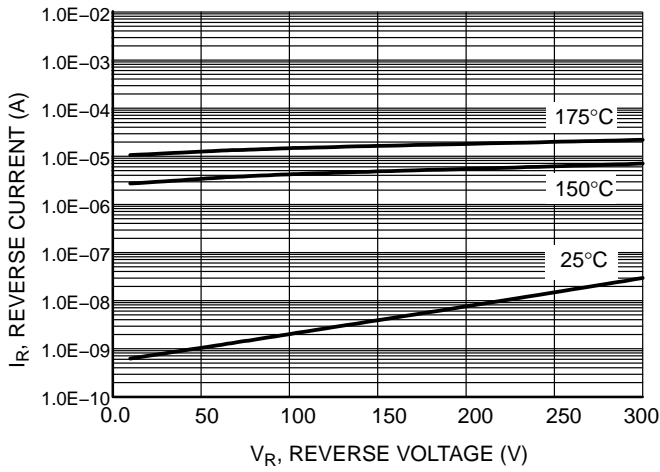


Figure 3. Typical Reverse Voltage

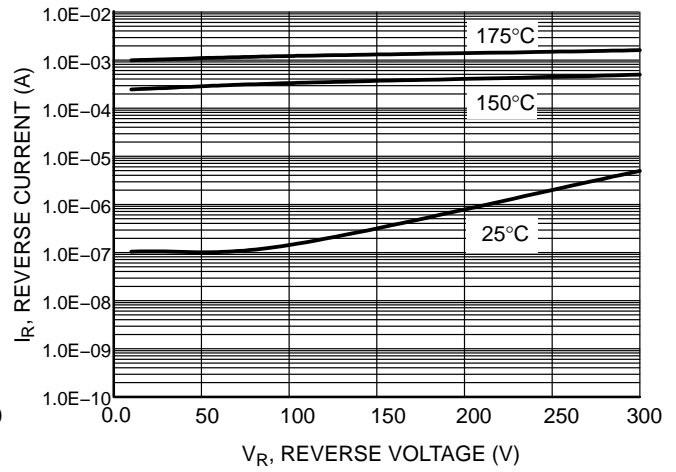


Figure 4. Maximum Reverse Voltage

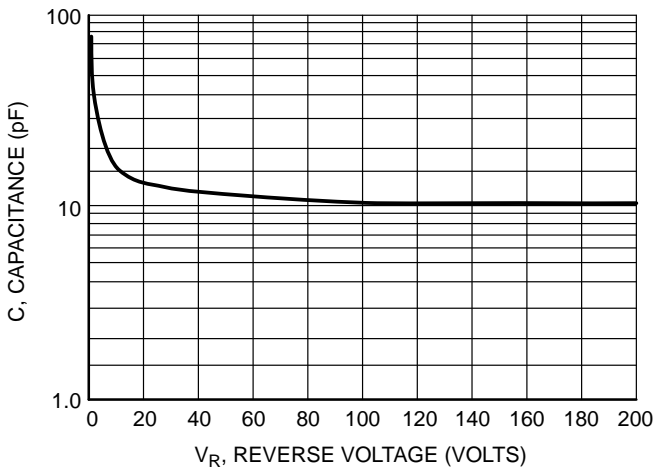


Figure 5. Typical Capacitance

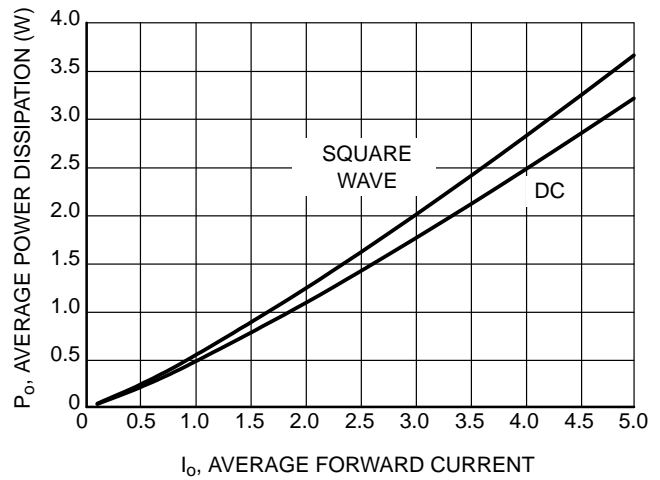


Figure 6. Power Dissipation

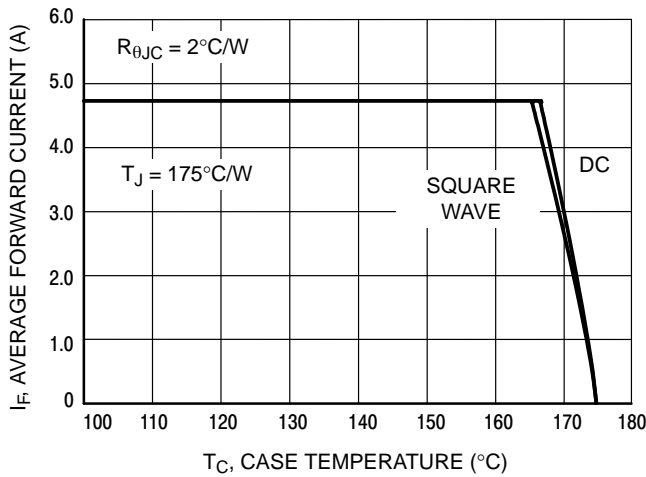


Figure 7. Current Derating, Case

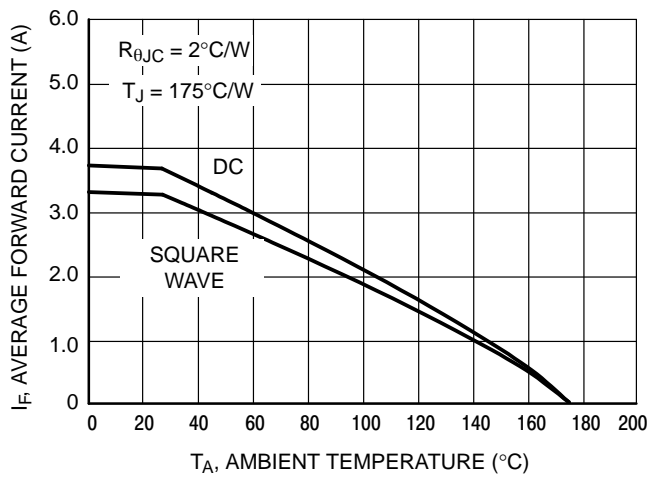
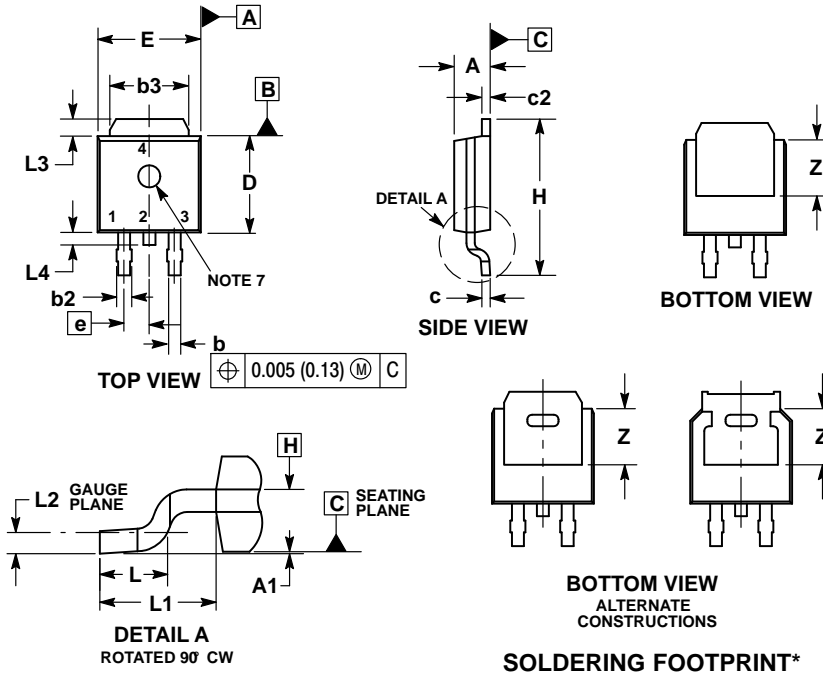


Figure 8. Current Derating, Ambient

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PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE) CASE 369C ISSUE F

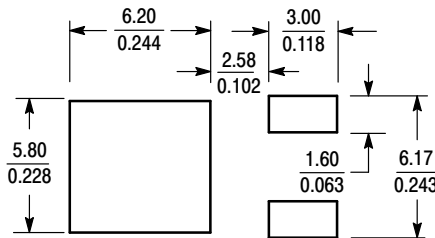


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

SOLDERING FOOTPRINT*



SCALE 3:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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